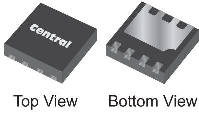
Material Composition Specification

TLM833S Case



Device average mass . . . . **24 mg**

Fluctuation margin . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	2.5%	0.6	Si	7440-21-3	2.5%	0.6	25,000
bond wire	gold	1.0%	0.24	Au	7440-57-5	1.0%	0.24	10,000
leadframe	Cu alloy w/ silver plating	30.9%	7.42	Cu	7440-50-8	30.1%	7.22	300,836
				Fe	7439-89-6	0.7%	0.173	7,208
				Zn	7440-66-6	0.04%	0.009	358
				Ag	7440-22-4	0.1%	0.015	637
die attach	silver epoxy	1.0%	0.24	epoxy resin	Proprietary	0.2%	0.05	2,083
				Ag	7440-22-4	0.8%	0.19	7,917
encapsulation*	EMC GREEN	55.0%	13.2	silica (fused)	60676-86-0	46.8%	11.22	467,504
				epoxy resin	Proprietary	3.5%	0.84	35,000
				epoxy, cresol novolac	29690-82-2	1.1%	0.263	10,954
				phenol resin	9003-35-4	3.5%	0.84	35,000
				carbon black	1333-86-4	0.2%	0.04	1,667
plating	matte tin	9.6%	2.3	Sn	7440-31-5	9.6%	2.3	95,834

*EMC GREEN molding compound is Halogen-Free.

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.